



Product Summary

$V_{(BR)DSS}$	$R_{DS(on)}$ TYP	I_D
-30V	30mΩ@-10V	-6A
	50mΩ@-4.5V	
30V	29mΩ@10V	6A
	40mΩ@4.5V	

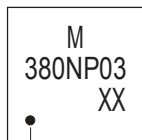
Feature

- Low drain-source ON-resistance
- High forward transfer admittance
- Low leakage current

Application

- Low voltage applications

MARKING:

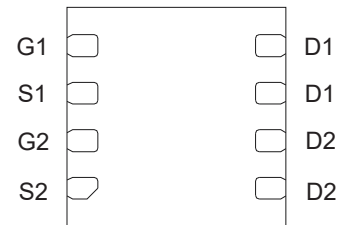


M380NP03 = Device Code
XX = Date Code

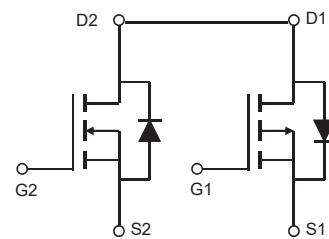
PIN 1

Preliminary

DFN3x3-8L



Schematic diagram



ABSOLUTE MAXIMUM RATINGS ($T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit	Test Condition
P-MOSFET				
Drain-Source Voltage	V_{DS}	-30	V	
Gate-Source Voltage	V_{GS}	± 20	V	
Continuous Drain Current ⁽¹⁾	I_D	-6	A	$T_A = 25^\circ\text{C}$
Pulsed Drain Current	I_{DM}	-24	A	
N-MOSFET				
Drain-Source Voltage	V_{DS}	30	V	
Gate-Source Voltage	V_{GS}	± 20	V	
Continuous Drain Current	I_D	6	A	$T_A = 25^\circ\text{C}$
Pulsed Drain Current ⁽¹⁾	I_{DM}	24	A	
Temperature and Thermal Resistance				
Thermal Resistance ⁽²⁾	$R_{\theta JA}$	44.6	$^\circ\text{C/W}$	from Junction to Ambient
Power Dissipation	P_D	2.8	W	$T_A = 25^\circ\text{C}$
Junction Temperature	T_J	150	$^\circ\text{C}$	
Storage Temperature	T_{STG}	-55~ +150	$^\circ\text{C}$	

P-channel MOSFET ELECTRICAL CHARACTERISTICS (T_a=25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Static Characteristics						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = -250μA	-30			V
Zero gate voltage drain current	I _{DSS}	V _{DS} = -24V, V _{GS} = 0V			-1	μA
Gate-body leakage current	I _{GSS}	V _{GS} = ±20V, V _{DS} = 0V			±100	nA
Gate threshold voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = -250μA	-1.4	-1.9	-2.4	V
Drain-source on-resistance ⁽³⁾	R _{DS(on)}	V _{GS} = -10V, I _D = -5A		30	38	mΩ
		V _{GS} = -4.5V, I _D = -4A		50	64	
Forward transconductance	g _{FS}	V _{DS} = -10V, I _D = -5A		16		S
Diode forward voltage ⁽³⁾	V _{DS}	I _S = -5A, V _{GS} = 0V			-1.2	V
Dynamic characteristics⁽⁴⁾						
Input Capacitance	C _{iss}	V _{DS} = -15V, V _{GS} = 0V, F = 1.0MHz		650		pF
Output Capacitance	C _{oss}			115		
Reverse Transfer Capacitance	C _{rss}			85		
Total gate charge	Q _g	V _{DS} = -15V, I _D = -5A, V _{GS} = -10V		15		nC
Gate-source charge	Q _{gs}			4		
Gate-drain charge	Q _{gd}			7.5		
Switching Characteristics⁽⁴⁾						
Turn-on delay time	t _{d(on)}	V _{DD} = -15V, I _D = -5A V _{GS} = -10V, R _{GEN} = 1Ω R _L = 30Ω			15	nS
Turn-on rise time	t _r				15	
Turn-off delay time	t _{d(off)}				70	
Turn-off fall time	t _f				25	

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N-channel MOSFET ELECTRICAL CHARACTERISTICS ($T_a=25^\circ\text{C}$ unless otherwise noted)

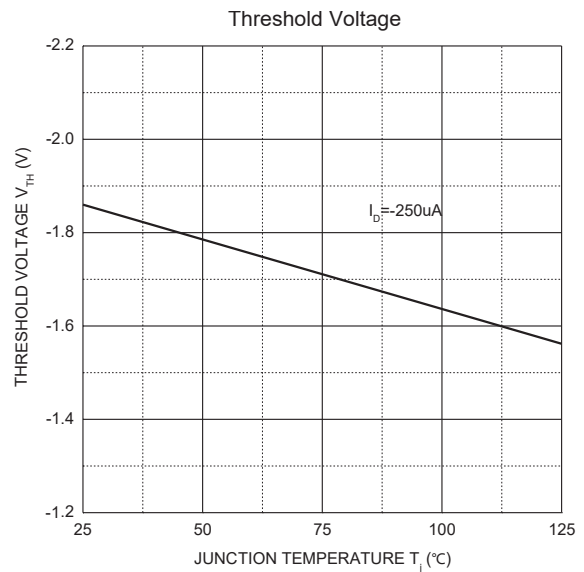
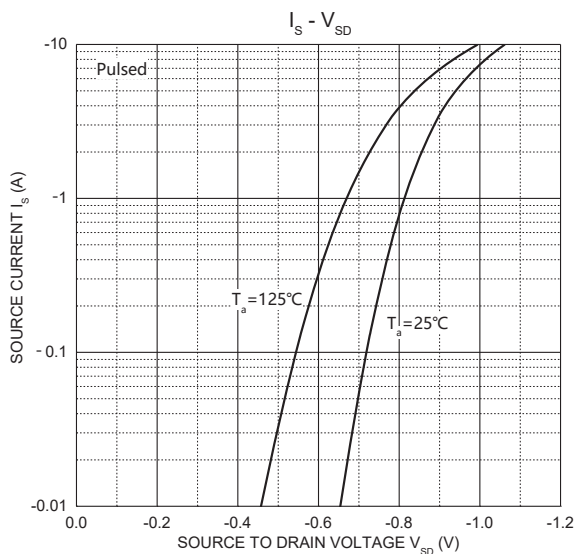
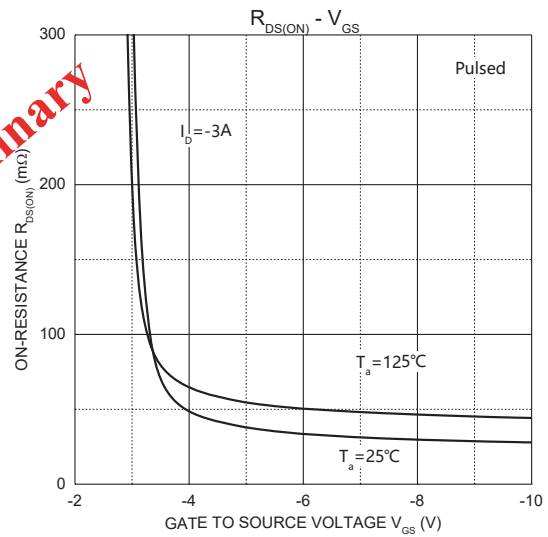
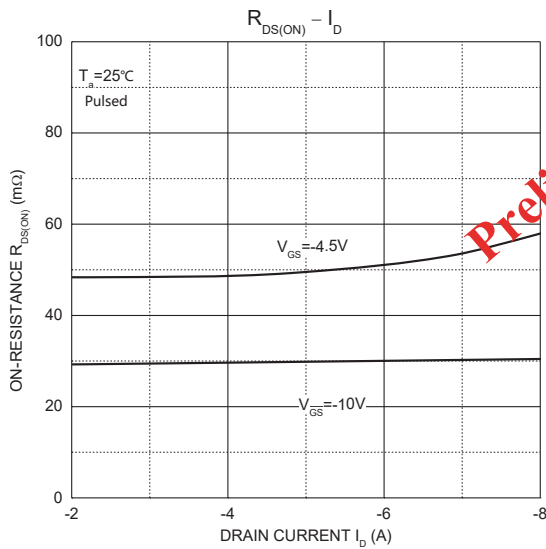
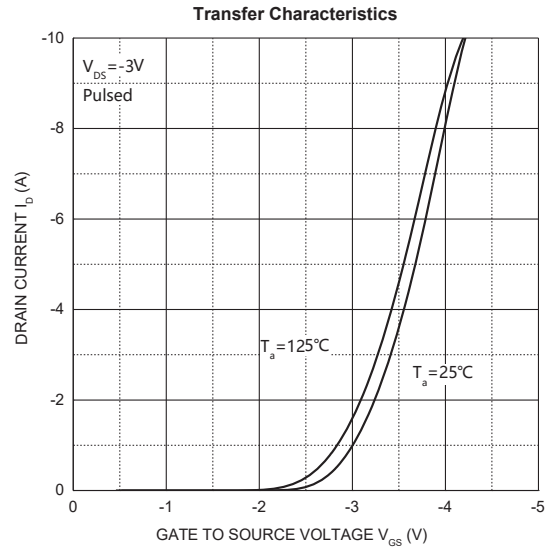
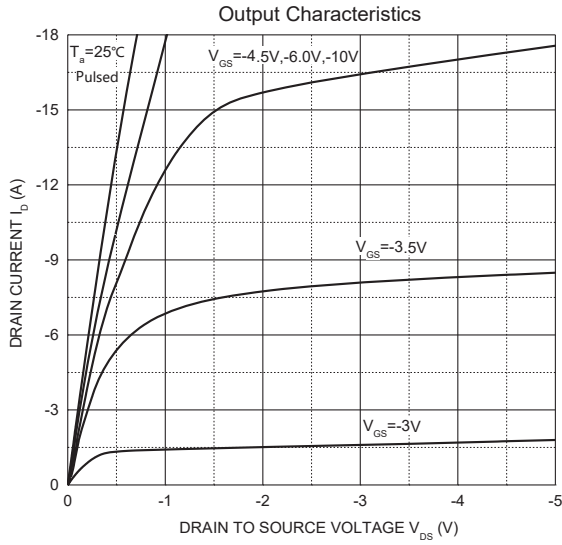
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Static Characteristics						
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	30			V
Zero gate voltage drain current	I_{DSS}	$V_{DS} = 24V, V_{GS} = 0V$			1	μA
Gate-body leakage current	I_{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$			± 100	nA
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1.0	1.5	2.0	V
Drain-source on-resistance ⁽³⁾	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 5A$		29	38	m Ω
		$V_{GS} = 4.5V, I_D = 5A$		40	52	
Forward transconductance	g_{FS}	$V_{DS} = 10V, I_D = 5A$		12		S
Diode Forward voltage ⁽³⁾	V_{DS}	$I_S = 5A, V_{GS} = 0V$			1.2	V
Dynamic characteristics⁽⁴⁾						
Input Capacitance	C_{iss}	$V_{DS} = 15V, V_{GS} = 0V, F = 1.0MHz$		310		pF
Output Capacitance	C_{oss}			82		
Reverse Transfer Capacitance	C_{rss}			36		
Total gate charge	Q_g	$V_{DS} = 15V, I_D = 5A, V_{GS} = 10V$		13		nC
Gate-source charge	Q_{gs}			3		
Gate-drain charge	Q_{gd}			4.5		
Switching Characteristics⁽⁴⁾						
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 15V, R_L = 8\Omega$ $V_{GS} = 10V, R_{GEN} = 3\Omega$			10	ns
Turn-on rise time	t_r				8	
Turn-off delay time	$t_{d(off)}$				30	
Turn-off fall time	t_f				5	

Notes:

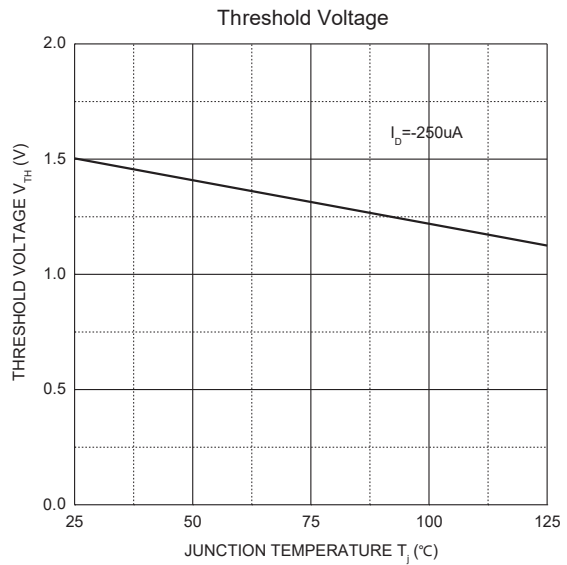
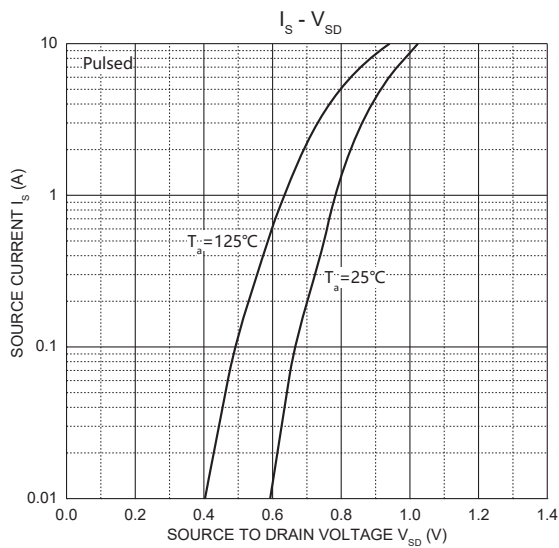
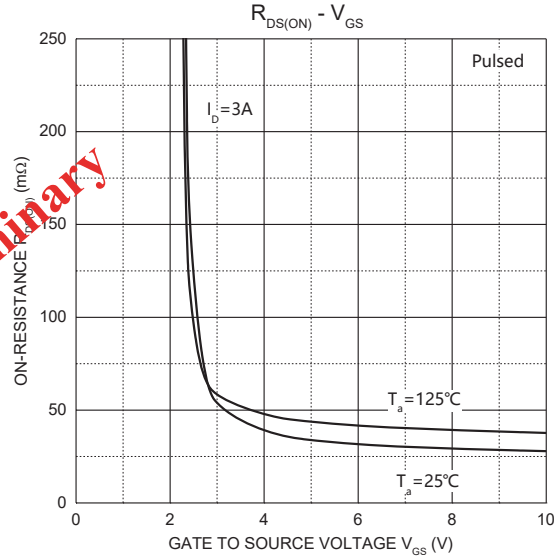
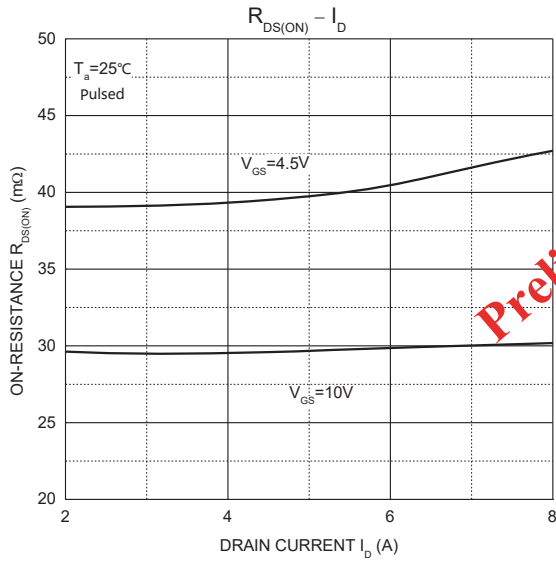
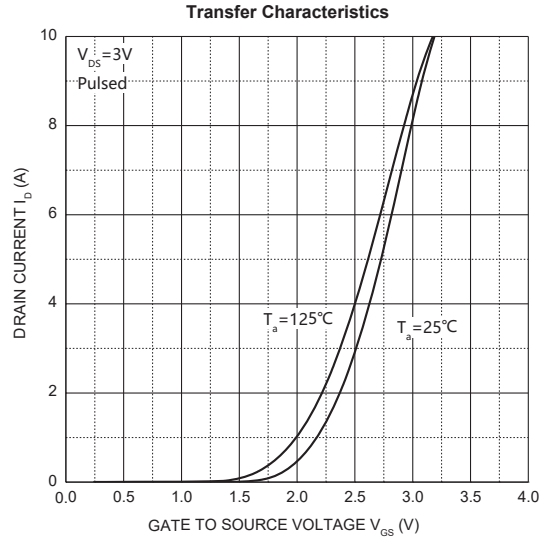
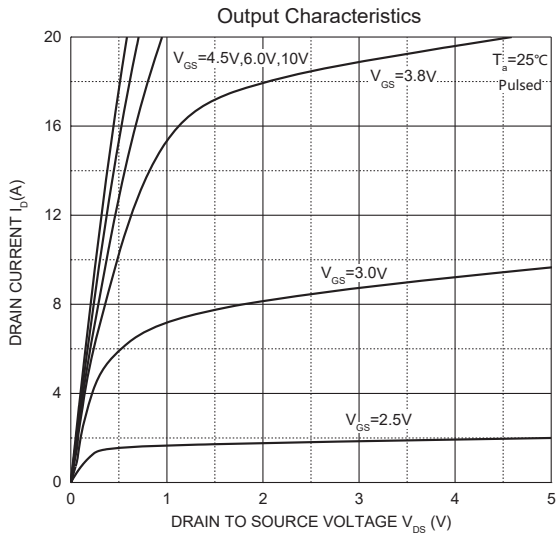
1. Repetitive Rating : Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t < 5$ sec.
3. Pulse Test : Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production testing.

Typical Electrical and Thermal Characteristics

P-Channel MOS

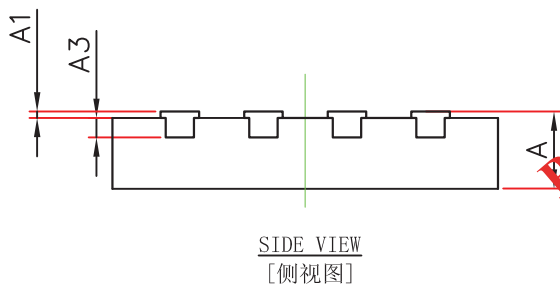
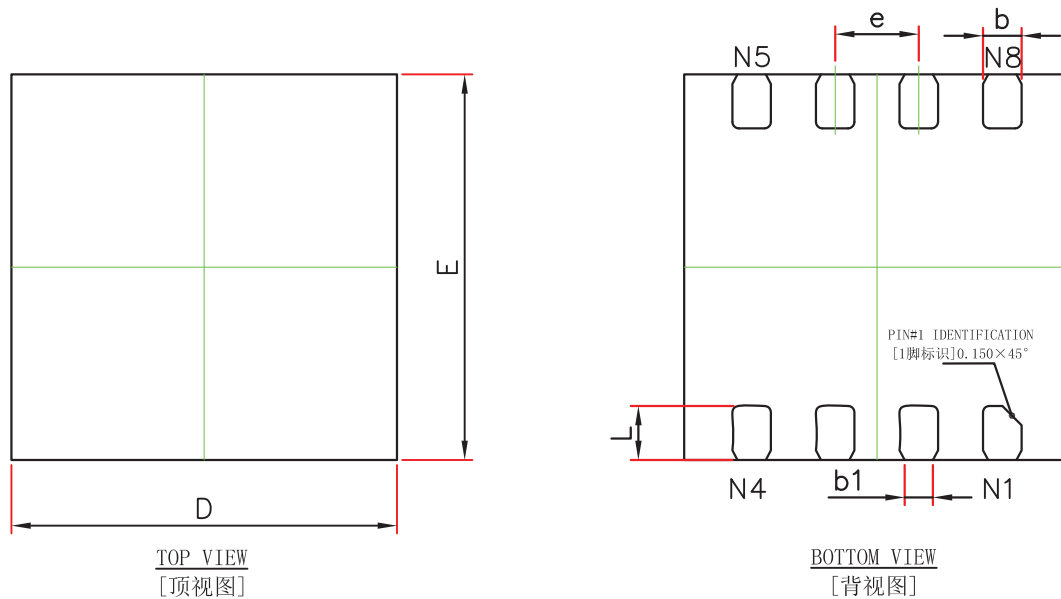


N-Channel MOS



Preliminary

DFN3X3-8L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.700	0.800	0.028	0.031
A1	0.000	0.050	0.000	0.002
A3	0.203REF.		0.008REF.	
D	2.900	3.100	0.114	0.122
E	2.900	3.100	0.114	0.122
b	0.250	0.350	0.010	0.014
b1	0.220REF.		0.009REF.	
e	0.650BSC.		0.026BSC.	
L	0.370	0.470	0.015	0.019